PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
Su-Chen LAI	05/12/2009
Ming-Yuan WU	05/12/2009
Kong-Beng THEI	06/01/2009
Harry Hak-Lay CHUANG	05/12/2009
Chiung-Han YEH	05/12/2009
Hong-Dyi CHANG	05/12/2009
Kuo Cheng CHENG	05/12/2009
Chien-Hung WU	06/02/2009
Tzung-Chi LEE	06/10/2009

RECEIVING PARTY DATA

Name:	TAIWAN SEMICONDUCTOR MANUFACTURING COMPANY
Street Address:	No. 8, Li-Hsin Rd. 6
Internal Address:	Science-Based Industrial Park
City:	Hsin-Chu
State/Country:	TAIWAN
Postal Code:	300-77

CH $40.00 12455509

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	12455509

CORRESPONDENCE DATA

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ATTORNEY DOCKET NUMBER:	24061.1119
NAME OF SUBMITTER:	David M. O'Dell

Total Attachments: 6
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Docket No.: 2008-0411 (-0413, -0414, -0417) / 24061.1119
Customer No.: 42717

ASSIGNMENT

WHEREAS, we,

(1) Su-Chen Lai of 7F-1, No. 30, Lane 59, Jiangong 1st Road, East District
Hsinchu City 300, Taiwan, R.O.C.

(2) Ming-Yuan Wu of No. 3, Dongshih Street
Hsinchu City 300, Taiwan, R.O.C.

(3) Kong Beng Thei of No. 186, Nan-Kang Road, Pao-Shan Village
Hsin-Chu Country, Taiwan, R.O.C.

(4) Harry Hak-Lay Chuang of 18-59 Lane 85, Fu-Chuan Street
Hsin-Chu City, Taiwan, R.O.C.

(5) Chiung-Han Yeh of No. 214, Dawu Street, North District
Tainan City 704, Taiwan, R.O.C.

(6) Hong-Dyi Chang of 2F, No. 11, Alley 2, Lane 244, Sec. 3
Roosevelt Rd., Taipei, Taiwan, R.O.C.

(7) Kuo Cheng Cheng of 6F, No. 38, Guancian Road
Baoshan Township, Hsinchu County 308, Taiwan, R.O.C.

(8) Chien-Hung Wu of No. 331, Wunnan Road, South District
Tainan City 702, Taiwan, R.O.C.

(9) Tzung-Chi Lee of 3F, No. 44-1, Lane 435, Sec. 1, Wunhua Road
Banciao City, Taipei County 220, Taiwan, R.O.C.

have invented certain improvements in

DUMMY GATE STRUCTURE FOR GATE LAST PROCESS

for which we have executed an application for Letters Patent of the United States of America,

X of even date filed herewith; and
X filed on 06/03/2009 and assigned application no. 12/455,509 and;

WHEREAS, we authorize the attorney of record to update this document to include Patent Office information as deemed necessary (i.e., filing date, serial number, etc.);

WHEREAS, Taiwan Semiconductor Manufacturing Company, Ltd., ("TSMC"), No. 8, Li-Hsin Rd. 6, Science-Based Industrial Park Hsin-Chu, Taiwan 300-77, Republic of China. is desirous of obtaining the entire right, title, and interest in, to and under the said invention and the said application in the United States of America and in any and all countries foreign thereto;

NOW, THEREFORE, for One Dollar ($1.00) and other good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, and other good and valuable consideration, we have sold, assigned, transferred and set over, and by these presents do hereby sell, assign, transfer and set over, unto the said TSMC, its successors, legal representatives, and assigns, the entire right, title, and interest in, to and under the said invention, and the said application, and all divisional, renewal, substitutional, and continuing applications thereof, and all Letters Patent of the United States of America which may be granted thereon and all reissues and extensions thereof, and all applications for Letters Patent which may be filed for said invention in any country or countries foreign to the United States of America, and all extensions, renewals, and reissues thereof, and all prior patents and patent applications from which a filing priority of the above-described patent application may be obtained, including the right to collect past damages; and we hereby authorize and request the Commissioner of Patents of the United States of America, and any official of any country or countries foreign to the United States of America, whose duty it is to issue patents on applications as aforesaid, to issue all Letters Patent for said invention to the said TSMC, its successors, legal representatives and assigns, in accordance with the terms of this instrument.

AND WE HEREBY covenant that we have full right to convey the entire interest herein assigned, and that we have not executed, and will not execute, any agreement in conflict herewith.

AND WE HEREBY further covenant and agree that we will communicate to said TSMC, its successors, legal representatives and assigns, any facts known to us respecting said invention, and testify in any legal proceedings, sign all lawful papers, execute all divisional, renewal, substitutional, continuing, and reissue applications, make all rightful declarations and/or oaths and generally do everything possible to aid the said TSMC, its successors, legal representatives and assigns, to obtain and enforce proper patent protection for said invention in all countries.

Inventor Name: Su-Chen Lai

Residence Address: 7F-1, No. 30, Lane 59, Jiangong 1st Road, East District
Hsinchu City 300, Taiwan, R.O.C.

Dated: 2009, 5, 12

Su-chen, Lai
Inventor Signature

Inventor Name: Ming-Yuan Wu

Residence Address: No. 3, Dongshih Street
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Dated: 5/12 '09. Ming-Yuan Wu.
Inventor Signature

Inventor Name: Kong-Beng Thei

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Dated: Chiung - Han Yeh 5/12 09'
Inventor Signature

Inventor Name: Ming-Yuan Wu

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Dated: 5/12 '09

Kuo Cheng-Cheng
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Inventor Name: Chien-Hung Wu

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Inventor Name: Tzung-Chi Lee

Residence Address: 3F, No. 44-1, Lane 435, Sec. 1, Wunhua Road
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Dated: 6/10 '09

Tzung-Chi lee
Inventor Signature

Inventor Name: Hong-Dyi Chang

Residence Address:
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______________, Taiwan, R.O.C.

Dated: ______________

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Inventor Signature

Inventor Name: Kuo Cheng Cheng

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Dated: ______________

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No. 331, Wunnan Road, South District
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Dated: 2009/06/02

Chien Hung Wu
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Dated: ______________

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Inventor Signature
